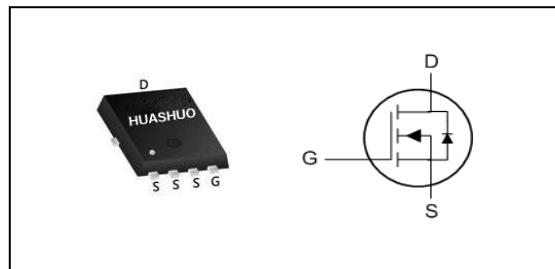


**N-Ch 100V Fast Switching MOSFETs**
**Description**

The HSBA0048 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the Synchronous Rectification for AC/DC Quick Charger.

**Product Summary**

V <sub>DS</sub>	100	V
R <sub>DS(ON),TYP</sub>	6.6	mΩ
I <sub>D</sub>	78	A

**PRPAK5X6 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current <sup>1,6</sup>	78	A
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current <sup>1,6</sup>	62	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	280	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	61	mJ
I <sub>AS</sub>	Avalanche Current	23	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	108	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t≤10s)	---	25	°C/W
	Thermal Resistance Junction-Ambient <sup>1</sup>	---	55	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	1.15	°C/W



**N-Ch 100V Fast Switching MOSFETs**

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=13.5\text{A}$	---	6.6	8	$\text{m}\Omega$
	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=4.5\text{V}$ , $I_D=11.5\text{A}$	---	8.7	10.5	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	---	2.3	V
$I_{\text{bss}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=20\text{A}$	---	85	---	S
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=13.5\text{A}$	---	45	---	$\text{nC}$
$Q_g$	Total Gate Charge (4.5V)		---	19.3	---	
$Q_{\text{gs}}$	Gate-Source Charge		---	9.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	4.8	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3\Omega$ , $I_D=13.5\text{A}$	---	10	---	$\text{ns}$
$T_r$	Rise Time		---	6.5	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	45	---	
$T_f$	Fall Time		---	7.5	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3320	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	605	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	20	---	

**Diode Characteristics**

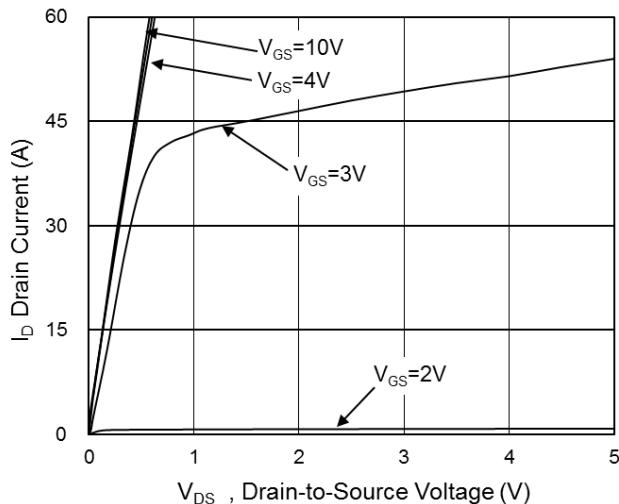
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5,6</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	48	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.1	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=13.5\text{A}$ , $\frac{dI}{dt}=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	33	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	150	---	nC

Note :

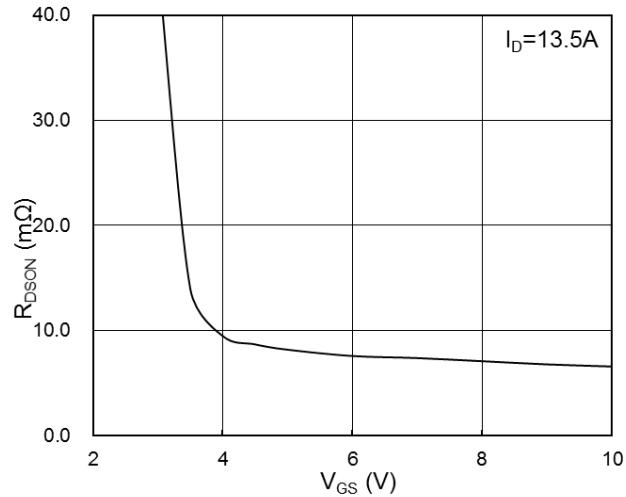
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.3\text{mH}$ ,  $I_{\text{AS}}=23\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.



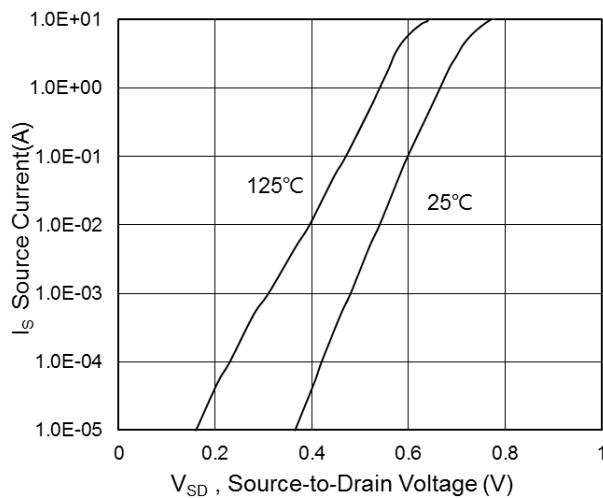
### Typical Characteristics



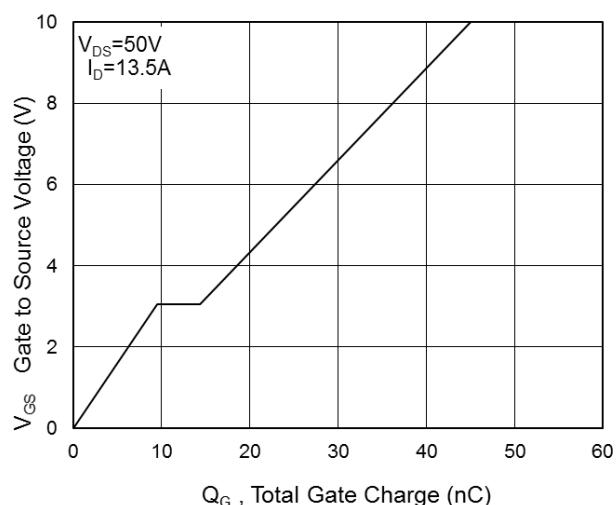
**Fig.1 Typical Output Characteristics**



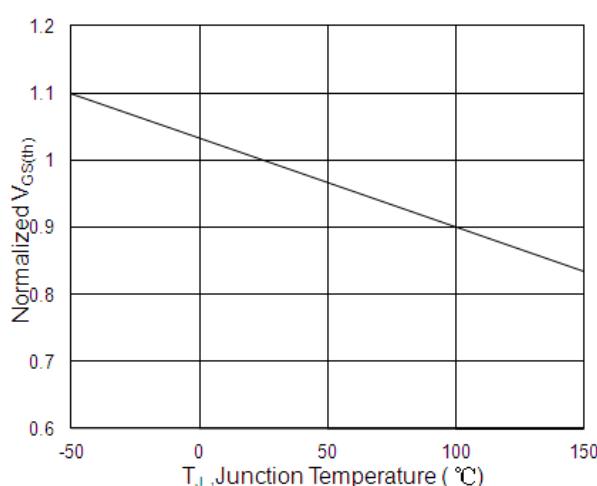
**Fig.2 On-Resistance vs G-S Voltage**



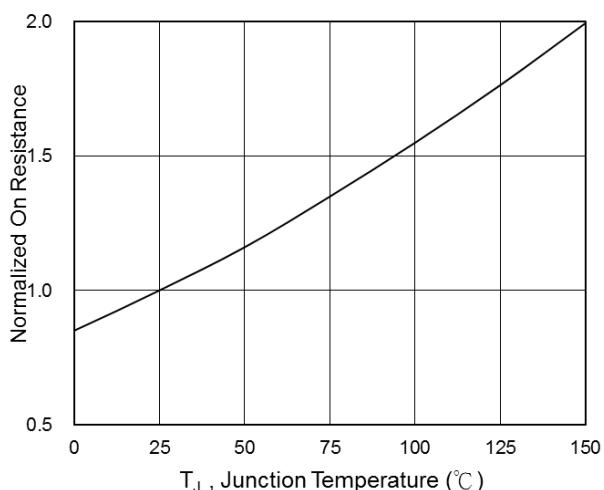
**Fig.3 Source-Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

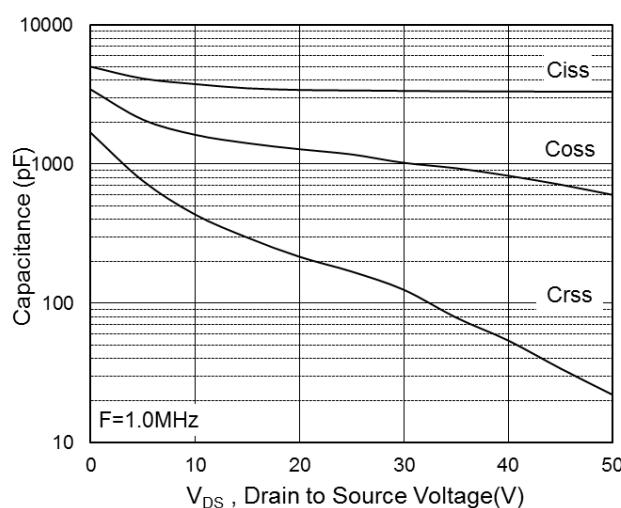


Fig.7 Capacitance

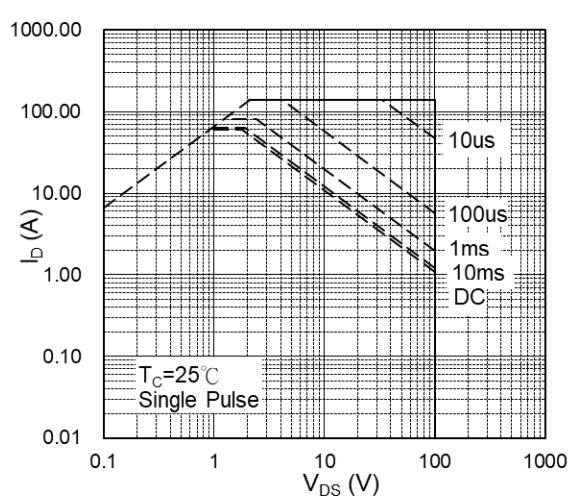


Fig.8 Safe Operating Area

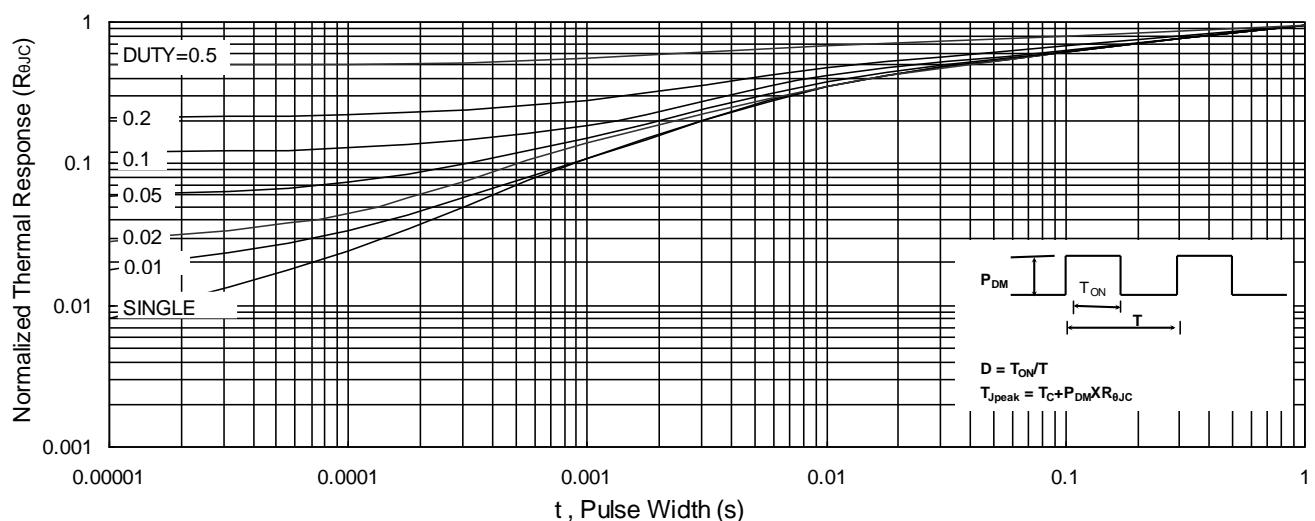


Fig.9 Normalized Maximum Transient Thermal Impedance

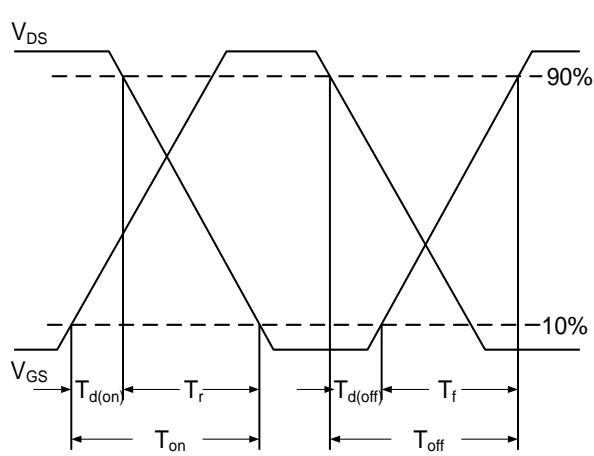


Fig.10 Switching Time Waveform

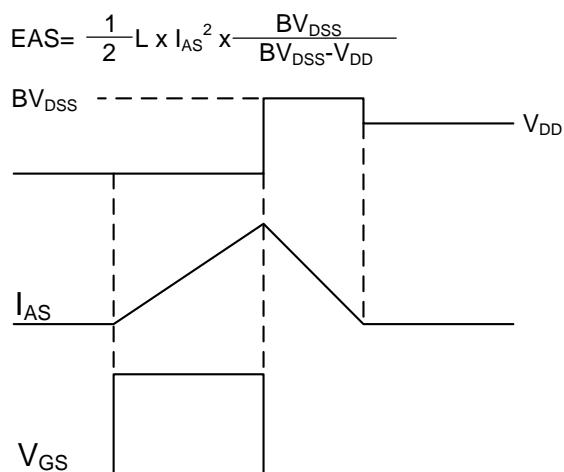
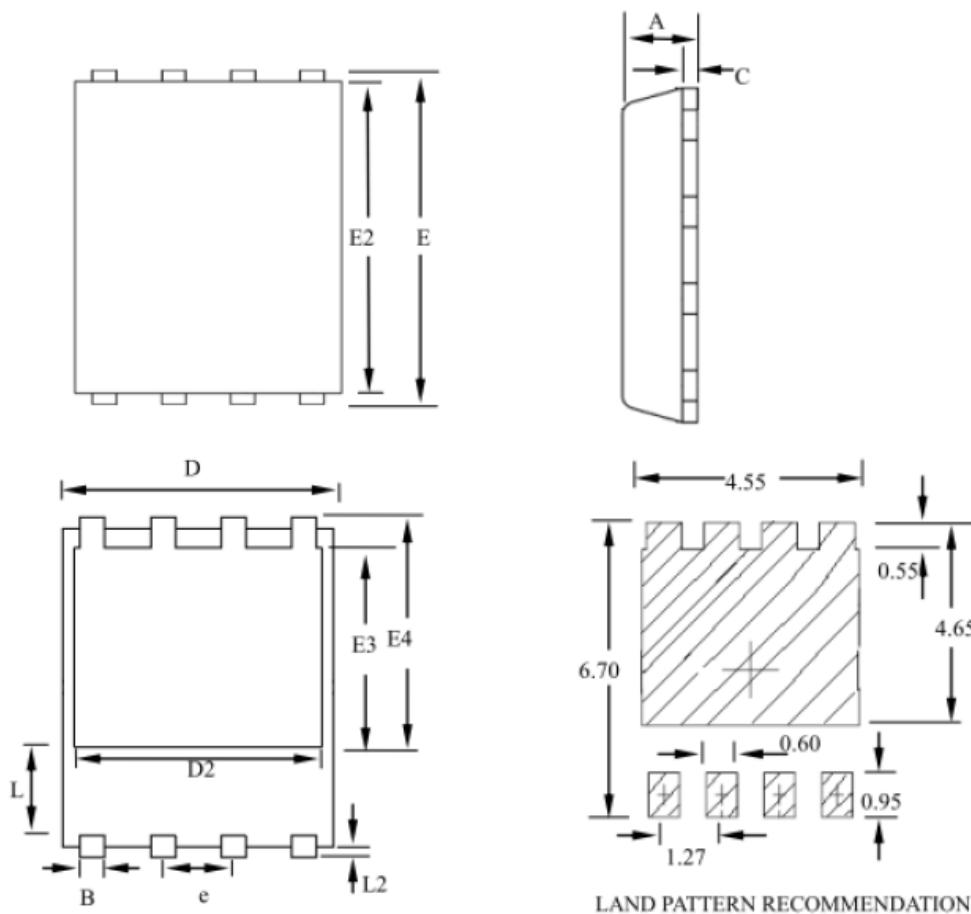


Fig.11 Unclamped Inductive Switching Waveform



## PRPAK5X6 Package Outline Dimensions



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145	--	0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--